

AMENDMENTS TO THE CLAIMS**In the Claims:**

The following listing of claims replaces all prior versions and listings of claims in the application.

Listing of Claims:

1. (Withdrawn – Currently amended) A wafer half-shell having a mouth delimited by at least one annular surface and one or more side walls, in which the mouth annular surface and the surfaces of the side wall have a substantially smooth surface finish, wherein the outer surface of the side wall has a ~~porous rough~~, continuous or discontinuous region which extends peripherally and is receded relative to the mouth annular surface of the half-shell.

2. (Withdrawn – Currently amended) A half-shell according to Claim 1, wherein the ~~porous rough~~ region is the surface resulting from the cutting of one or more radial walls connected to the side wall of the half-shell in a receded position relative to the annular surface defining the mouth of the half-shell.

3. (Withdrawn – Original) A half-shell according to Claim 2, obtained by cutting from an intermediate wafer comprising a plurality of half-shells interconnected by at least one interconnecting wall extending from the side wall of each half-shell and connected to the half-shells in a receded position relative to the annular mouth surface.

4. (Withdrawn – Original) A half-shell according to Claim 1, wherein said annular surface comprises centering means adapted to fit with complementary centering means of a complementary half-shell.

5. (Withdrawn – Original) A half-shell according to Claim 4, wherein said centering means comprise tapered annular coupling surfaces or coupling surfaces having a U, V, L-shaped profile or a toothed, Greek-key pattern or zigzag profile.

6. (Withdrawn – Original) A wafer comprising a plurality of half-shells with at least one containing side wall and interconnected by at least one interconnecting wall, wherein the

interconnecting wall is connected to the half-shells in a receded position relative to the annular mouth surface of each half-shell.

7. (Withdrawn – Original) A wafer according to Claim 6, wherein the half-shells are interconnected by means of a plurality of interconnecting walls (8a, 8b) which extend from the containing side walls (10) of the half-shells.

8. (Currently amended) A food product ~~comprising a half-shell~~ according to Claim ~~[[1]]~~ 9, ~~and including further comprising~~ a mass of filling contained in the pair of half-shells.

9. (Currently amended) A food product ~~according to Claim 8~~, comprising a pair of half-shells, fitted together mouth to mouth and including a mass of filling, wherein at least one of the half-shells is a wafer half-shell having a mouth delimited by at least one annular surface and one or more side walls, in which the mouth annular surface and the surfaces of the side wall have a substantially smooth surface finish, wherein the outer surface of the side wall has a ~~porous rough~~, continuous or discontinuous region which extends peripherally and is receded relative to the mouth annular surface of the half-shell.

10. (Original) A food product comprising at least two wafer half-shells coupled one to the other along annular mating surfaces defining their mouth profile, wherein said annular mating surfaces of each of said half-shells have centering means complementary one to the other and wherein at least one of said half-shells has an outer side wall with a rough, continuous or discontinuous region extending peripherally, which is receded relative to the mating annular surface of said half-shell.

11. (Original) A food product according to Claim 10, wherein said centering means comprise formations susceptible of mutual engagement.

12. (Previously presented) A food product according to Claim 10, wherein said centering means comprise annular mating surfaces having a toothed profile, a U-shaped profile, a V-shaped profile, a L-shaped profile, a Greek-key pattern profile or a zigzag profile.

13. (Previously presented) A food product according to Claim 10, wherein said centering means comprise tapered annular mating surfaces.

14. (Canceled).

15. (Original) A food product according to claim 10, wherein said annular mating surfaces and the surface of said centering means have a smooth surface finish.

16. (Withdrawn – Currently amended) A method for the preparation of a wafer half-shell with a mouth and a containing side wall, comprising the steps of:

- preparing a wafer comprising a plurality of the half-shells connected by at least one interconnecting wall connected to the half-shells in a receded position relative to the annular mouth surface of the half-shells, and
- separating the individual half-shells from the interconnecting wall by cutting in a direction perpendicular to the general plane of the interconnecting wall to form a rough region extending peripherally around an outer surface of the side wall.

17. (Withdrawn – Previously presented) A method according to Claim 16, wherein the wafer is a product produced by baking a wafer batter in a mould.

18. (New) A food product according to Claim 9, wherein the rough region is the surface resulting from the cutting of one or more radial walls connected to the side wall of the half-shell in a receded position relative to the annular surface defining the mouth of the half-shell.

19. (New) A food product according to Claim 10, wherein the rough region is the surface resulting from the cutting of one or more radial walls connected to the side wall of the half-shell in a receded position relative to the annular surface defining the mouth of the half-shell.